Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**(Side View)**

**ANODE**

**.024 X .024”**

**.042”**

**.042”**

**CHIP BACK IS CATHODE**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size .024 x .024”**

**Backside Potential: Cathode**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .019” X .019” DATE: 8/31/21**

**MFG: CDI THICKNESS .008” P/N: 1N645**

**DG 10.1.2**

#### Rev B, 7/19/02